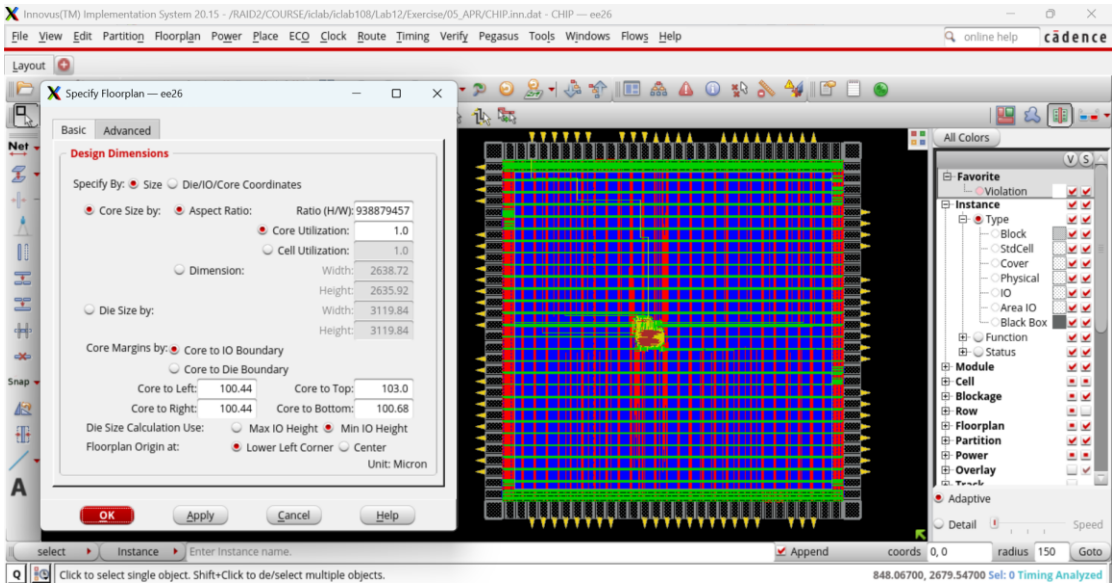
# ICLAB Lab12 Report

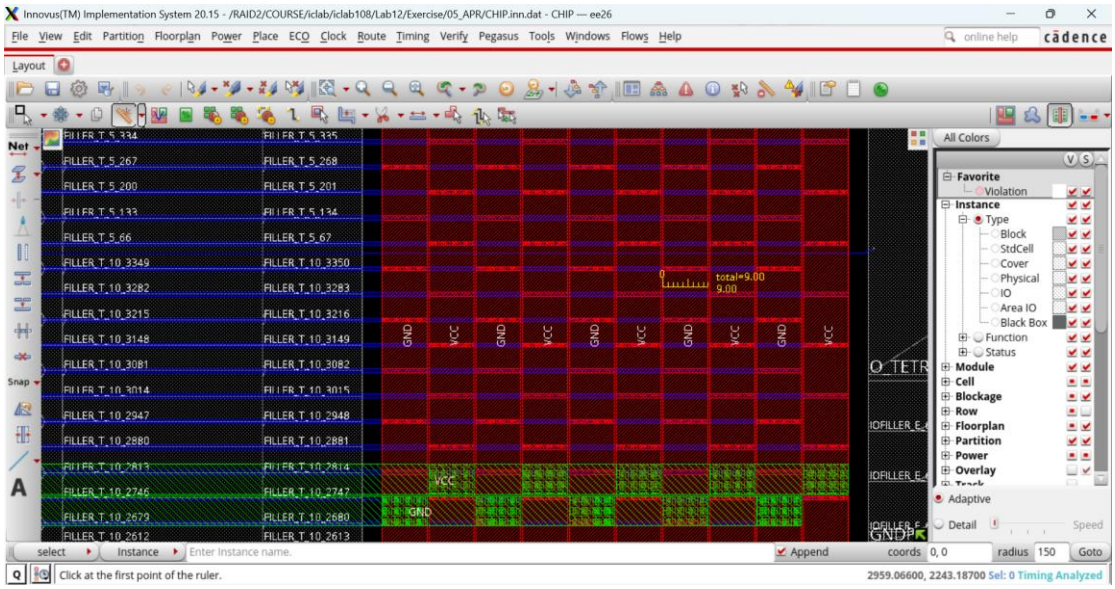
帳號 ：iclab108

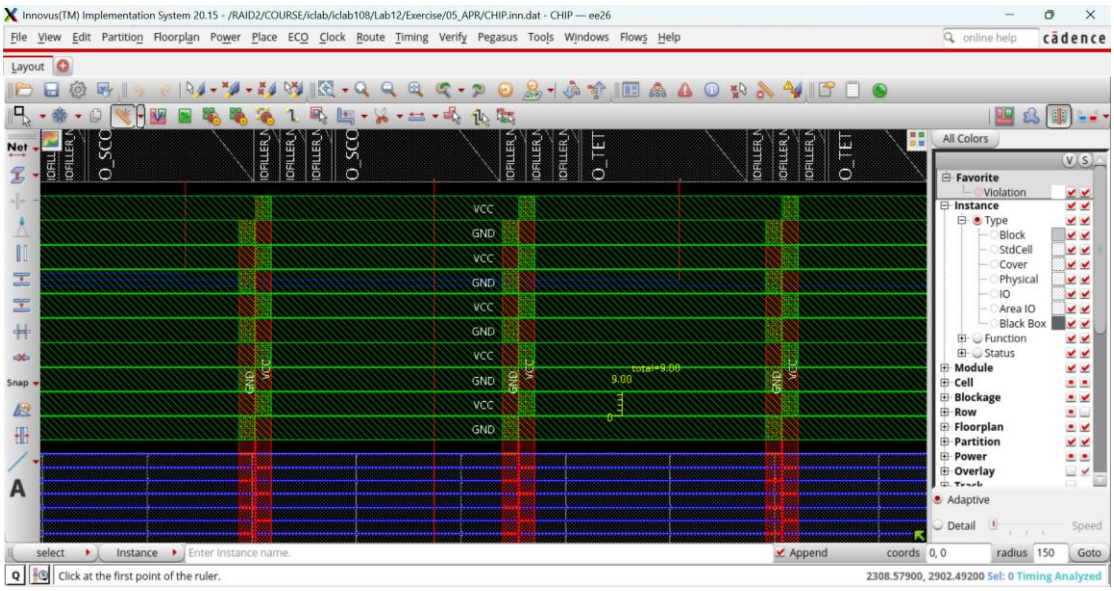
110511277 蔡東宏

1. Core to IO boundary:

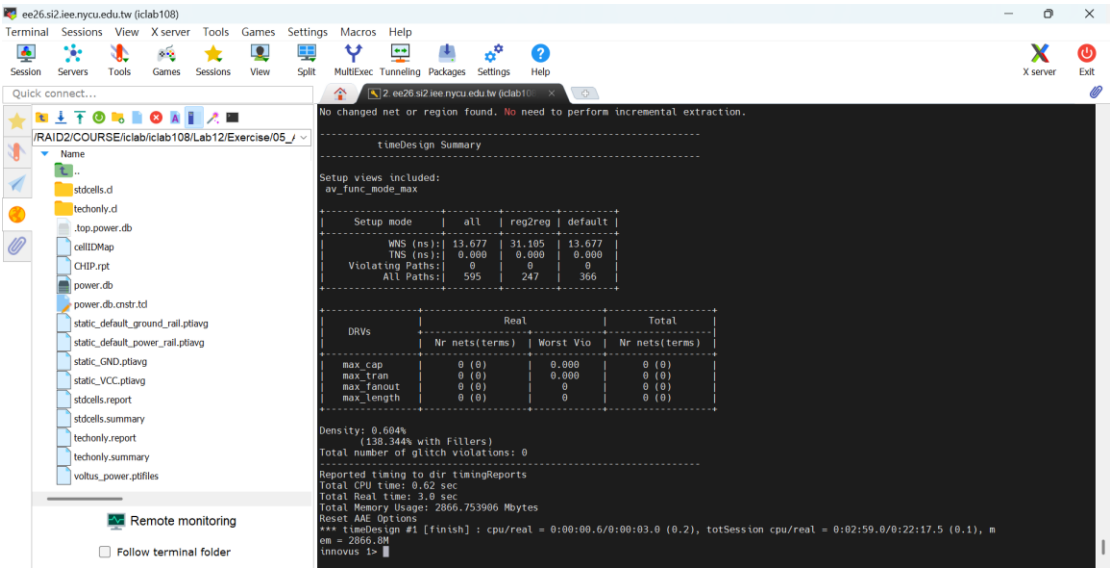



2. Core Ring:

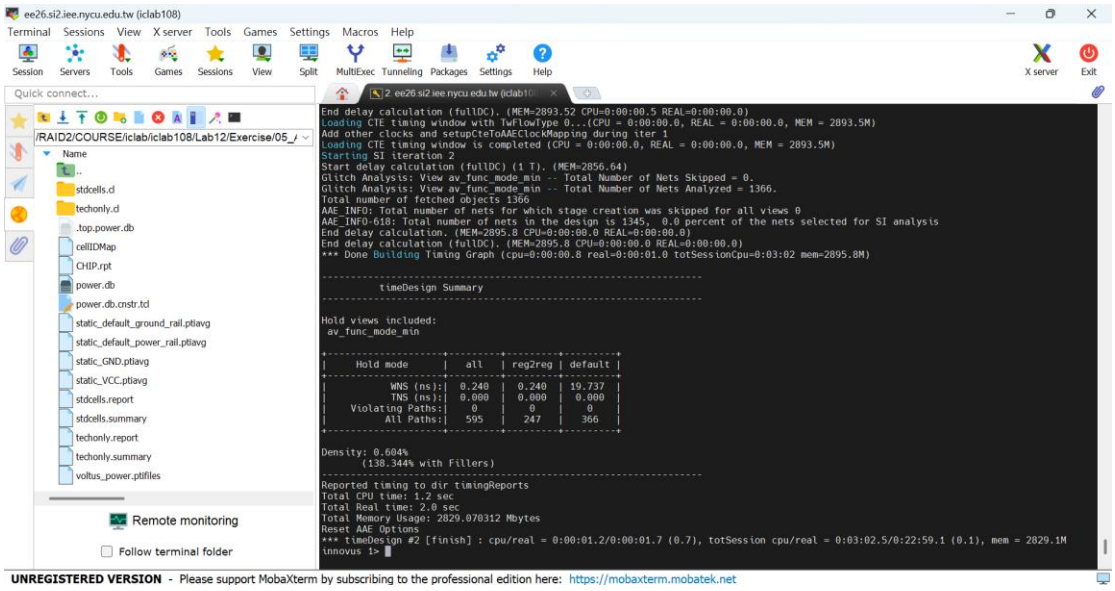




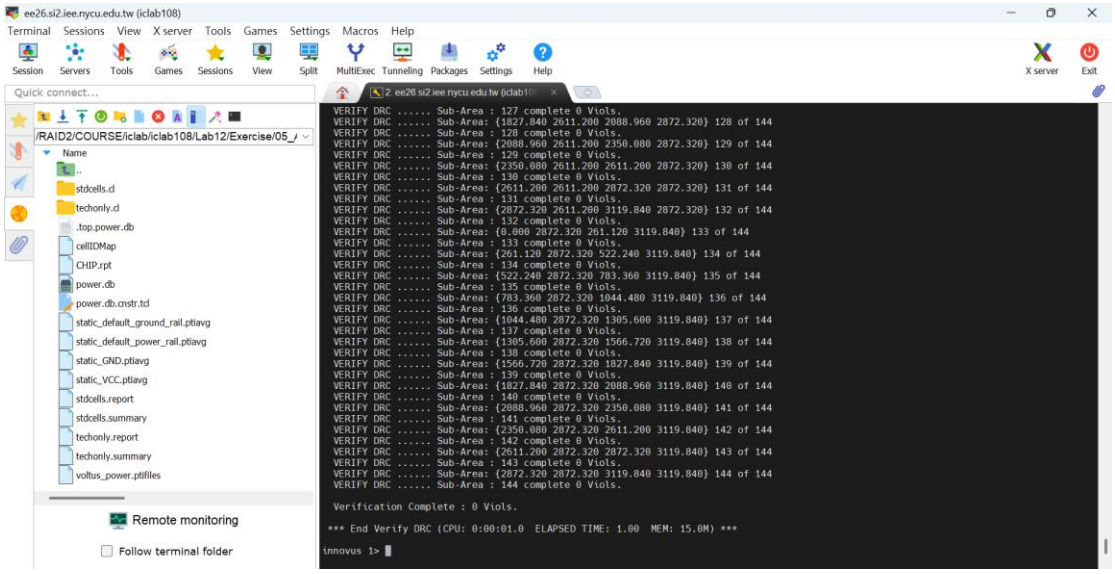

3. Post-Route setup time analysis:



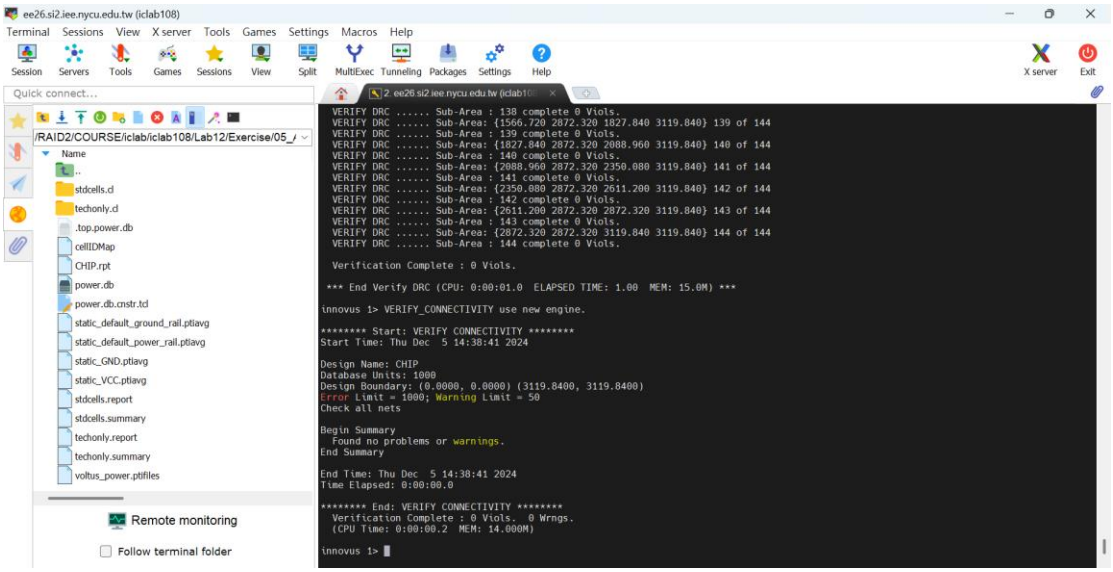
4. Post-Route hold time analysis:



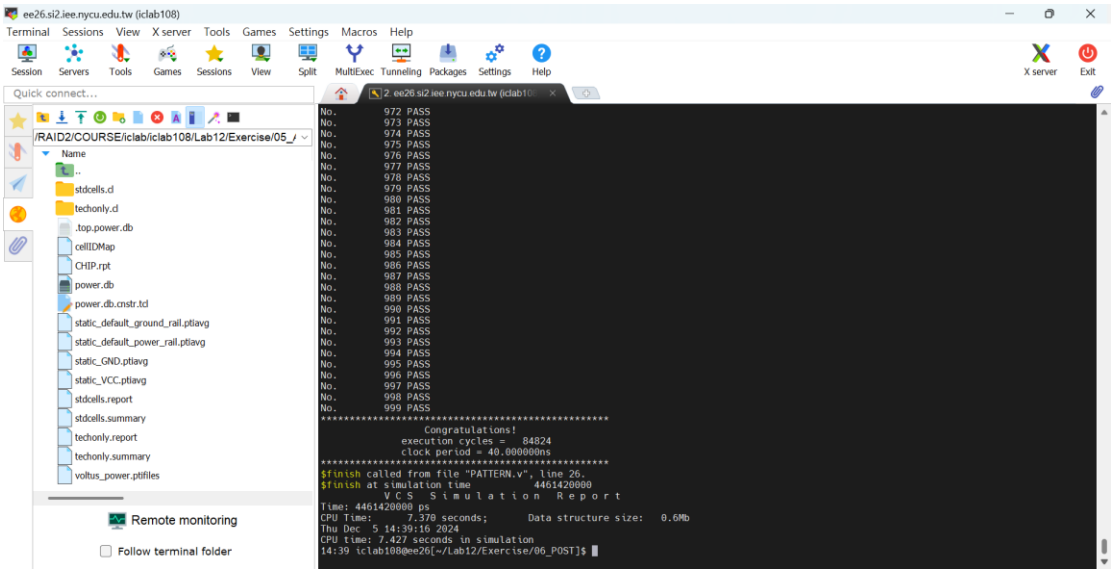

5. DRC result :



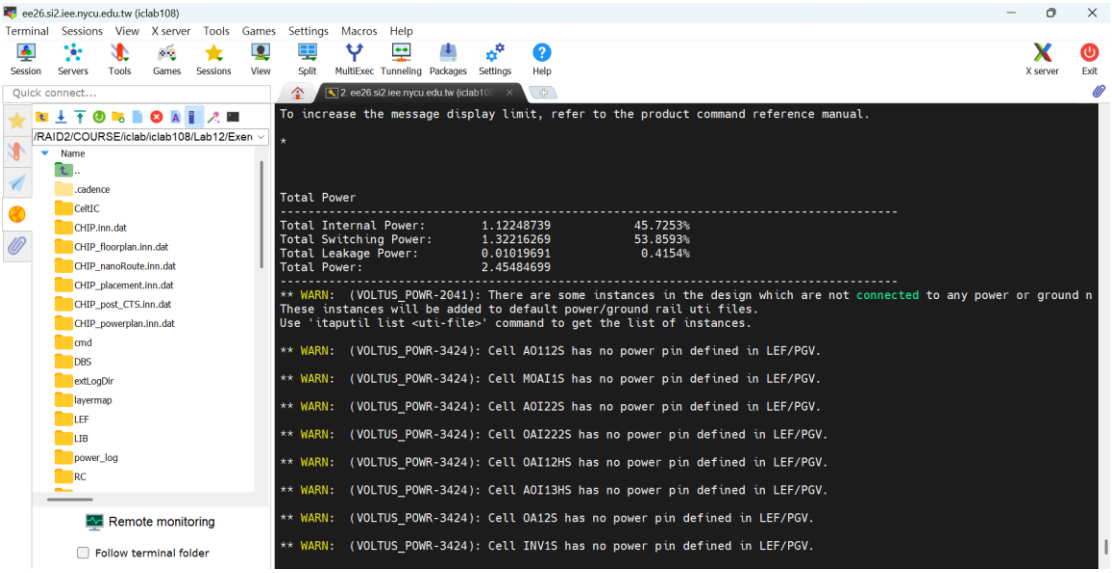
6. LVS result :



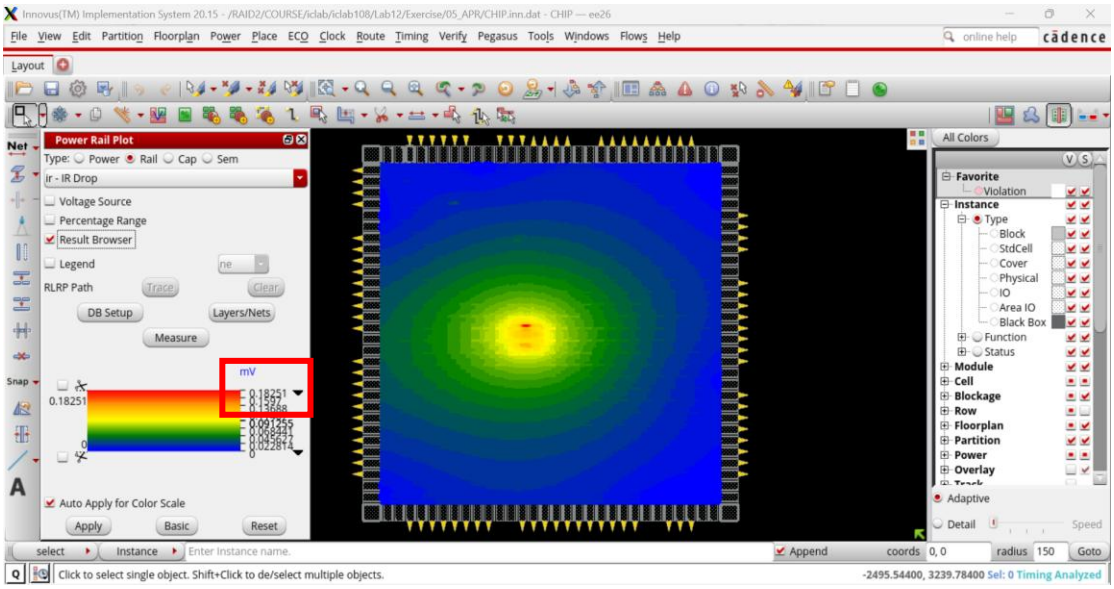

7. Post Layout simulation results :



8. Power result :




9. IR Drop results :




在一條金屬導線上，若寄生電阻太大，將導致 IR drop 的現象，如果未能有效的減少 IR drop，會造成電源供應不足，影響晶片效能。因此我使用了 8 組 core power pad 以及使用更粗的電源線 stripe 去減少 IR drop。